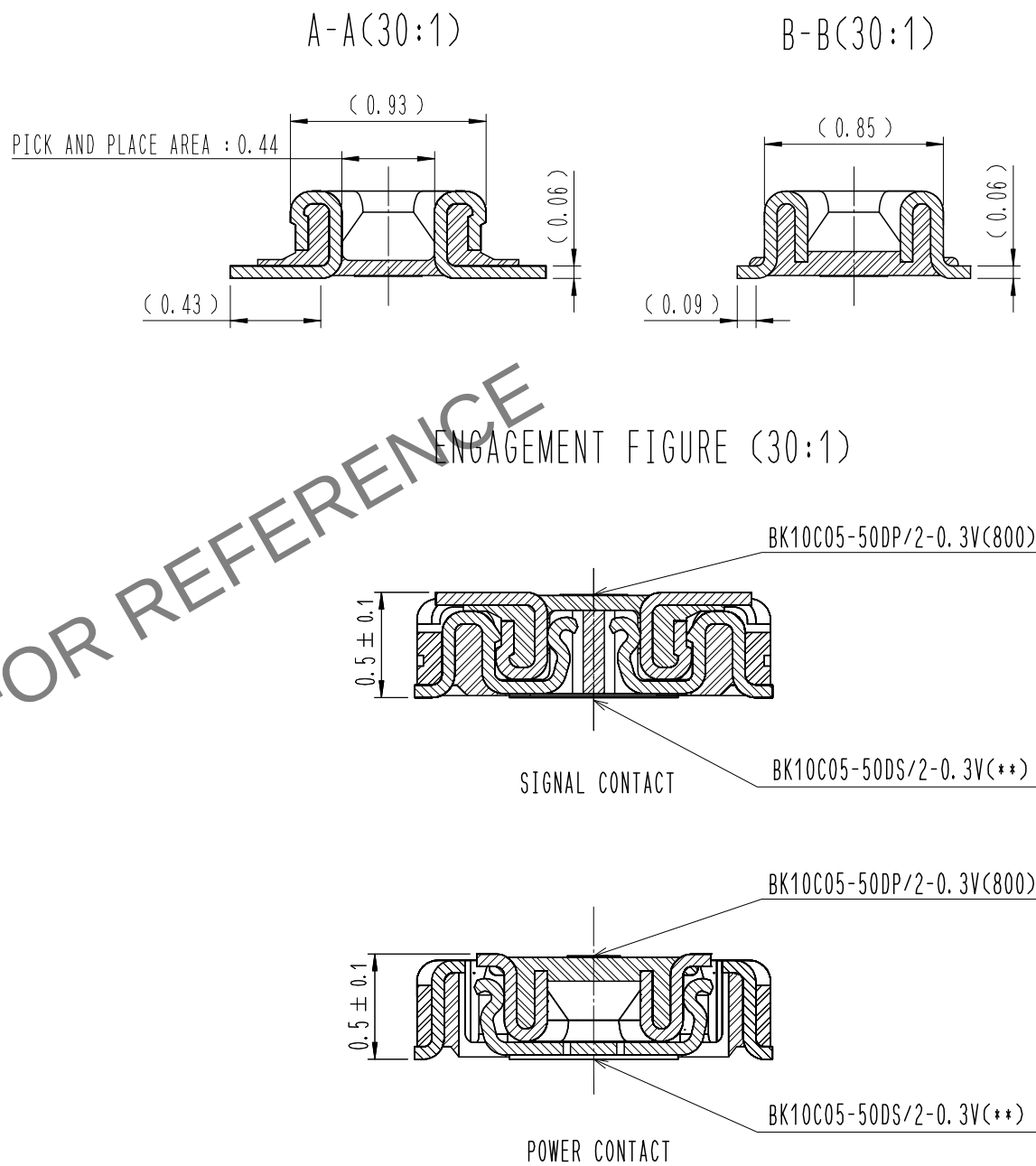
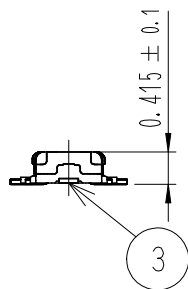
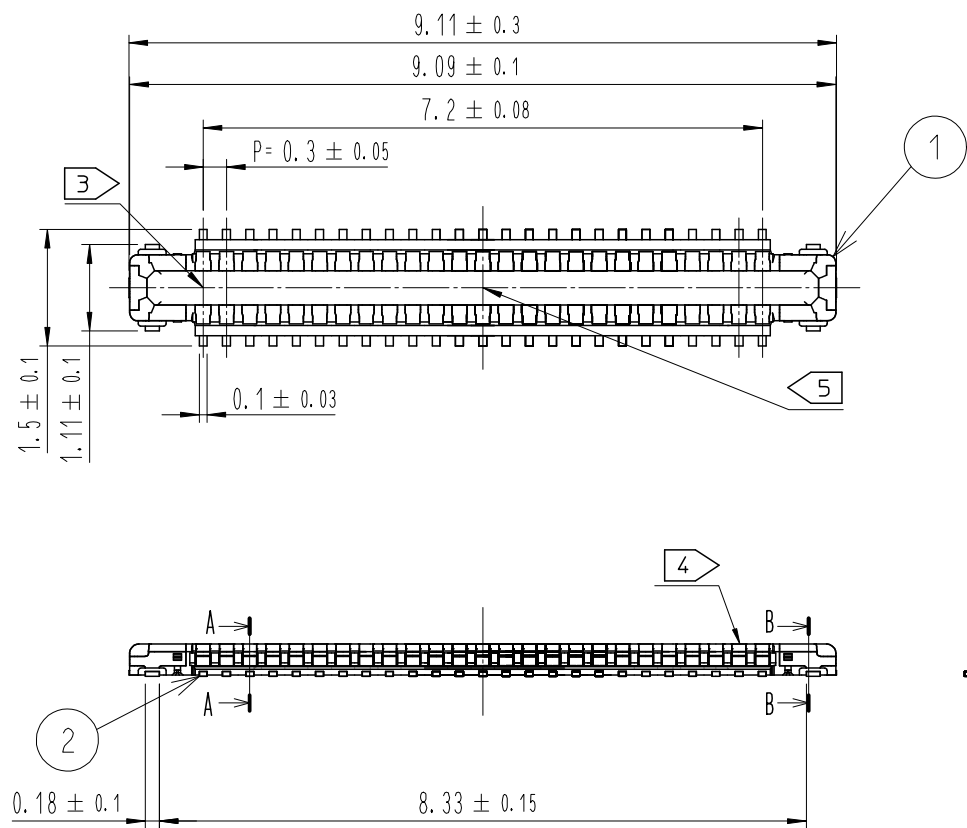


A
B
C
D
E
F



DRAWING FOR REFERENCE
This is subject to change without notice

- NOTE 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
- 1 2 CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μm MIN
SMT LEAD : GOLD 0.05 μm MIN
(NO GOLD PLATING IS ACCEPTABLE EXCEPT CONTACT POINTS AND SMT LEADS)
UNDERPLATING : NICKEL 1 μm MIN
(SURFACE : SEALING)
- 3 CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
- 4 A PART OF THE WALL COULD BE NOTCHED
- 5 DENT EXISTS IN THE INDICATED AREA FOR MANUFACTURING CONVENIENCE.

COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE
△	1	RE-6-3439		JDW	JHW	24.01.18	△				. .
△					. .	△					. .
△					. .	△					. .

A-A(30:1)

LACE AREA : 0.44

(0.93)

(0.06)

(0.43)

B-B(30:1)

(0.85)

(0.06)

(0.09)

ENGAGEMENT FIGURE (30:1)

BK10C05-50DP/2-0.3V(800)

0.5 ± 0.1

SIGNAL CONTACT

BK10C05-50DS/2-0.3V(**)

BK10C05-50DP/2-0.3V(800)

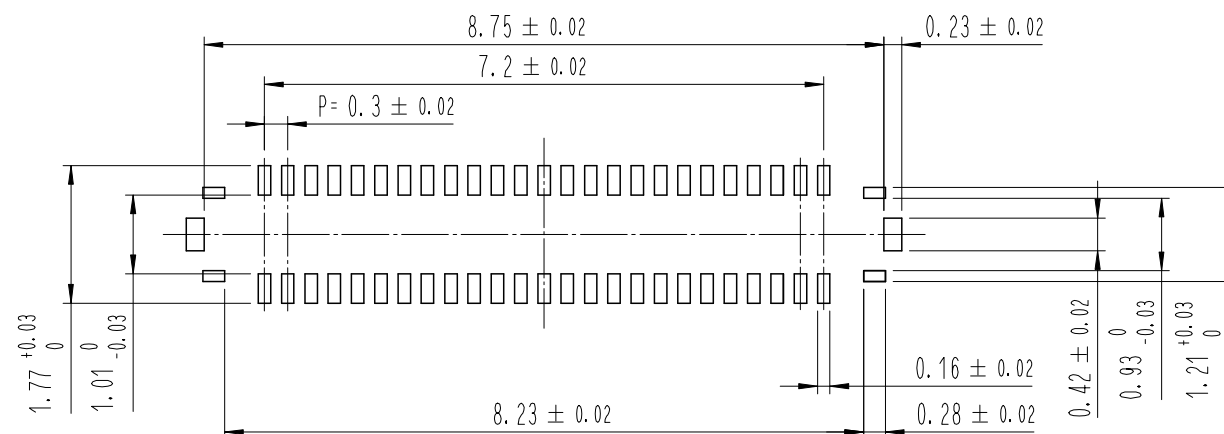
0.5 ± 0.1

POWER CONTACT

BK10C05-50DS/2-0.3V(**)

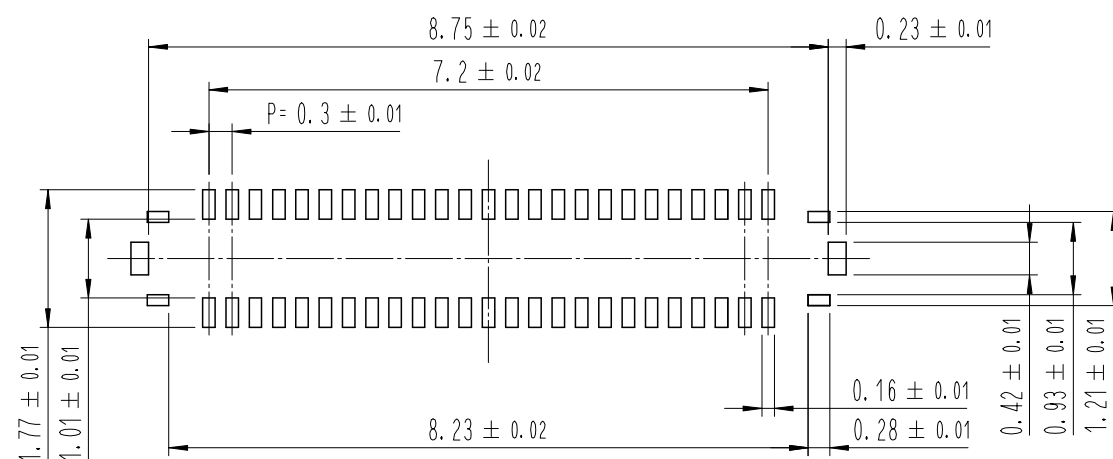
4	PS	CLEAR (EMBOSSED CARRIER TAPE)						
3	COPPER ALLOY	2						
2	COPPER ALLOY	2						
1	LCP	UL94 V-0, BLACK	6	PS	BLACK (PLASTIC REEL)			
			5	POLYESTER	CLEAR (COVER TAPE)			
NO.	MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS		
REMARKS				DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
				S. H. PARK	S. H. PARK	Y. J. LEE	H. W. JO	22.11.30
				22.11.30	22.11.30	22.11.30	22.11.30	
CODE NO. (OLD)				DRAWING NO.		PART NO.		
				EDC3-633583-80		BK10C05-50DP/2-0.3V(800)		
SCALE				UNITS		CODE NO		
10:1				mm		CL 6666-0063-1-800		
HRS HIROSE KOREA CO., LTD.						1/3		

7 RECOMMENDED PCB LAYOUT

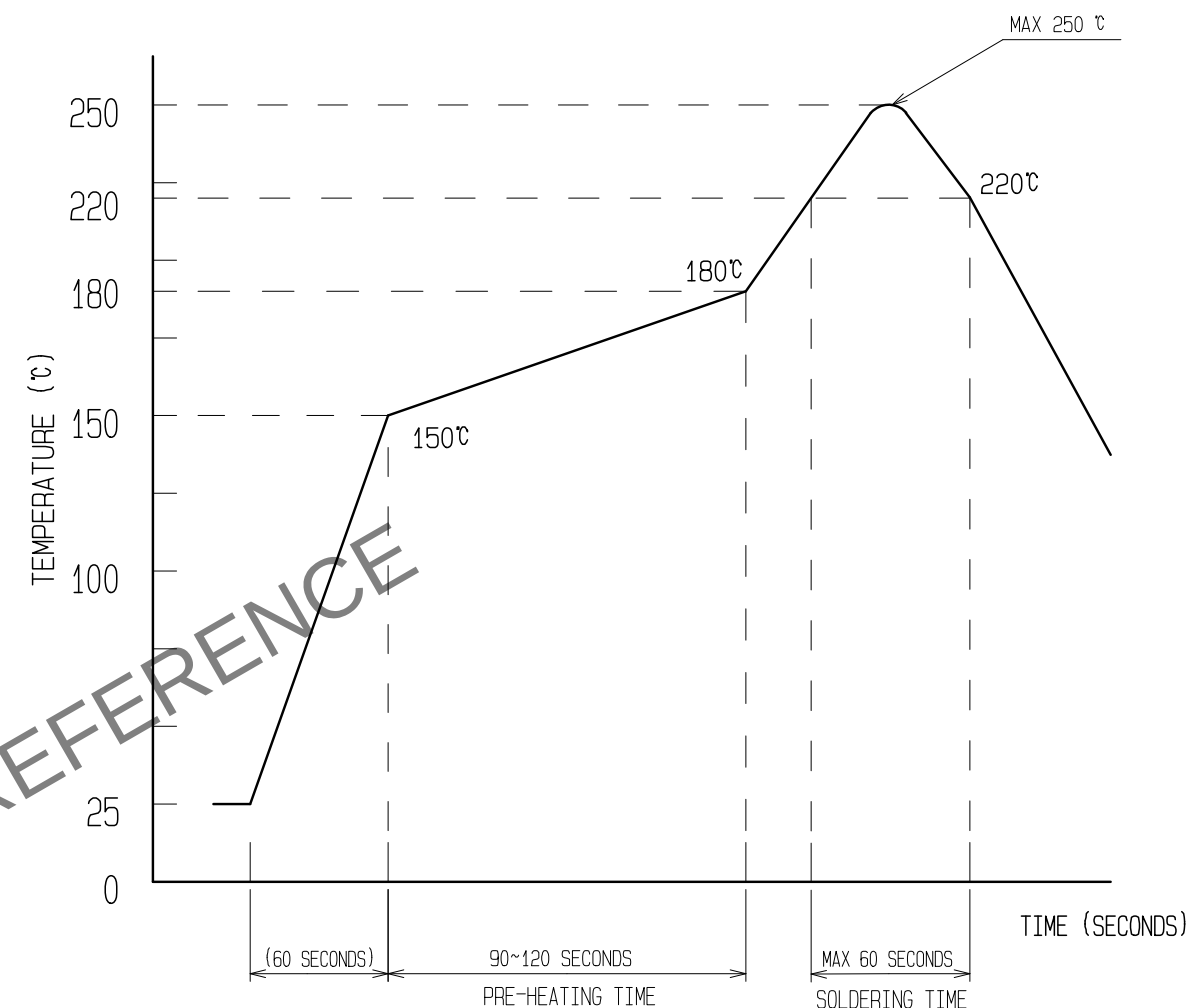


RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : $80 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.

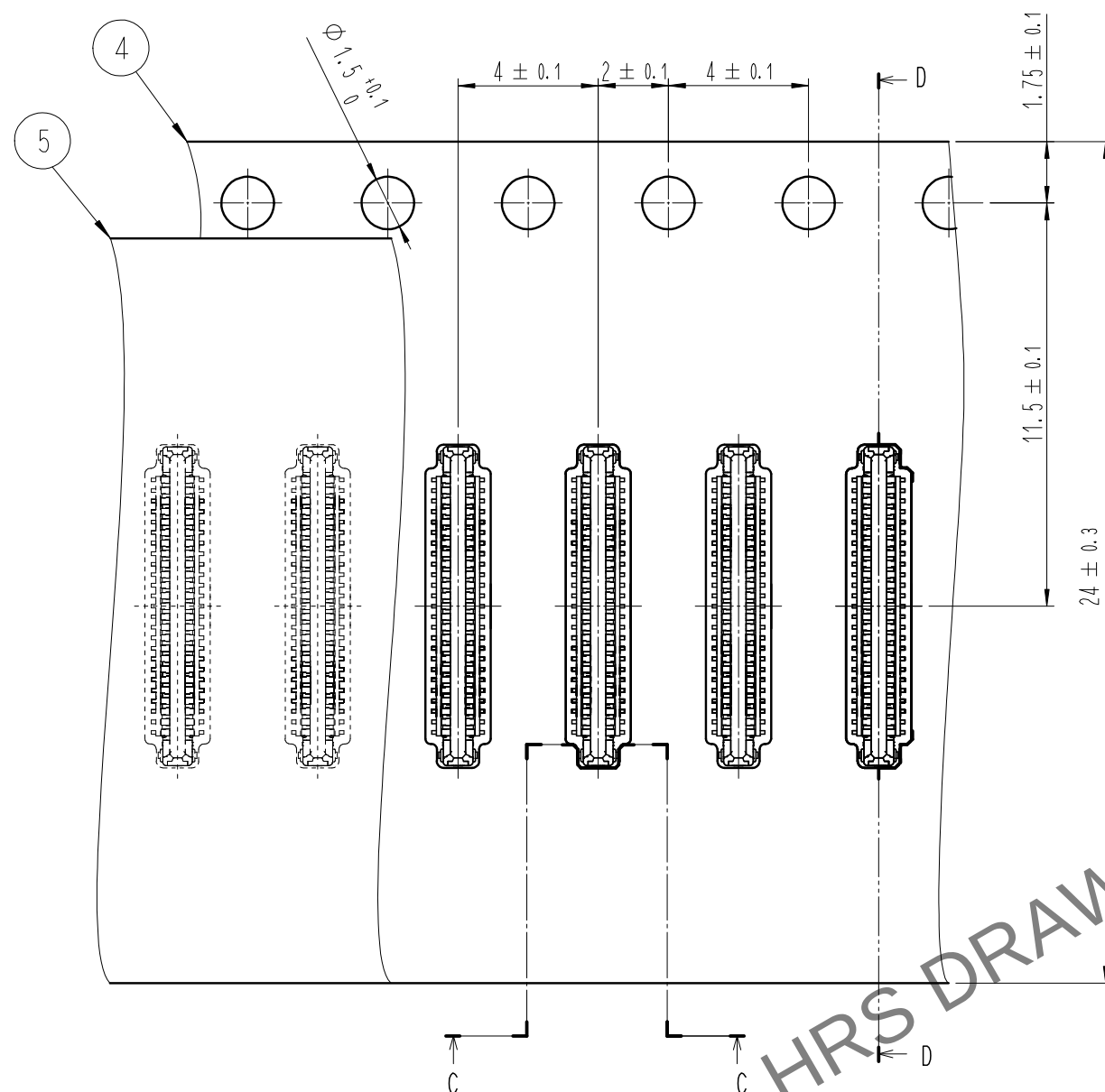


REFLOW METHOD : N_2 REFLOW
NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
1) REFLOW TIME
DURATION ABOVE 220°C , 60 SEC MAX.
(PEAK TEMPERATURE : 250°C MAX)
2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

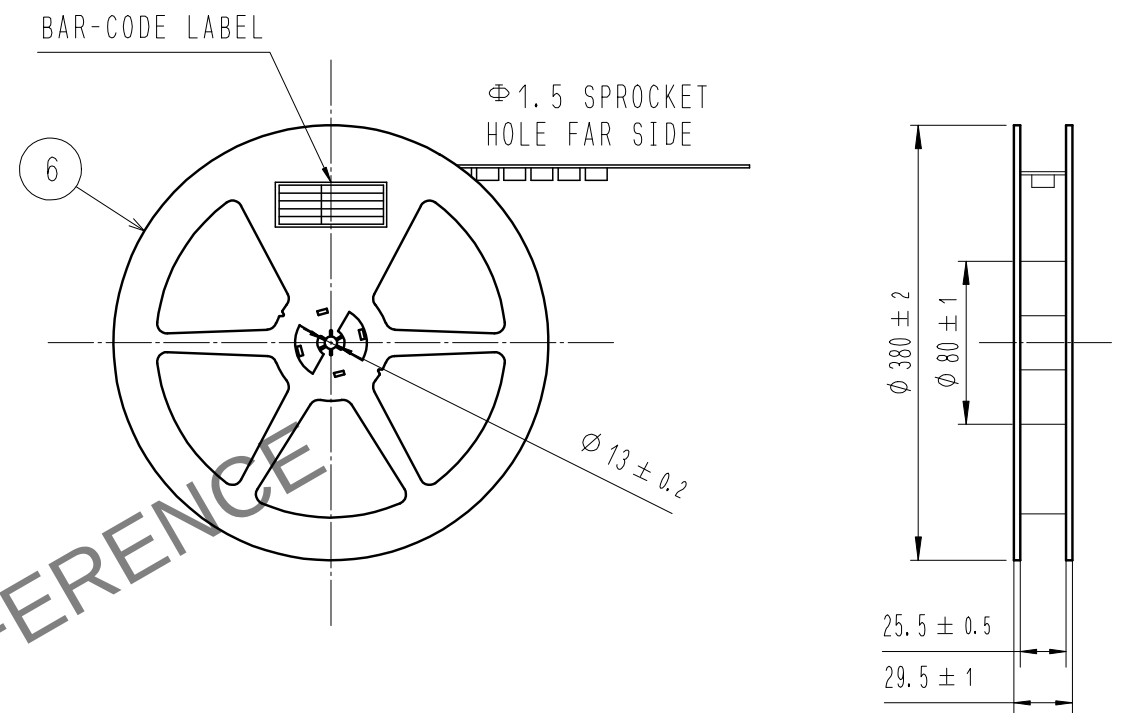
- 6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.
- 8 . THIS PRODUCT SATISFIES HALOGEN FREE REQUIREMENTS DEFINED AS 900ppm MAXIMUM CHLORINE, 900ppm MAXIMUM BROMINE, AND 1500ppm MAXIMUM TOTAL OF CHLORINE AND BROMINE.
- 9 . THIS PRODUCT COMPLY WITH RoHS.

	DRAWING NO.	EDC3-633583-80	PART NO.	BK10C05-50DP/2-0.3V(800)
	SCALE	10:1	CODE NO	CL 6666-0063-1-800
	UNITS	mm		

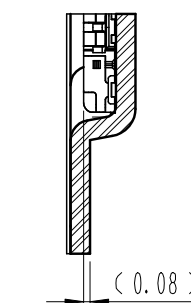
EMBOSSSED CARRIER TAPE PACKAGING (5:1)



STYLE AND DIMENSION OF REEL (FREE)



DETAIL OF PART No. LABEL



SUPPLIER	
QUANTITY	
PART NO.	
CODE NO.	
DATE OF MANUFACTURED	
生産月日	年 月 日
図番	** ** *
品名	BK10C05-50DP/2-0.3V(800)
納入数量	20,000個
納入者	HIROSE KOREA

10 . PER REEL 20,000 CONNECTORS.
11 . THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.
12 ➤ REFER TO JIS C 0806, IEC-60286-3 (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)

	DRAWING NO. EDC3-633583-80		PART NO. BK10C05-50DP/2-0.3V(800)	
	SCALE 10:1		CODE NO	
	 HIROSE KOREA CO., LTD.		CL 6666-0063-1-800	
UNITS mm				